

Features

- Low Forward Voltage Drop
- Guard Ring Construction for Transient Protection
- Low Capacitance
- Ultra-Small Surface Mount Package
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

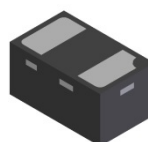
Mechanical Data

- Case: X1-DFN1006-2
- Case Material: Molded Plastic, "Green" Molding Compound.
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Dot
- Terminals: Finish—NiPdAu Annealed over Copper Leadframe.
Solderable per MIL-STD-202, Method 208 ^(e4)
- Weight: 0.001 grams (Approximate)

X1-DFN1006-2



Top View



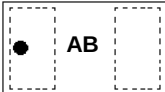
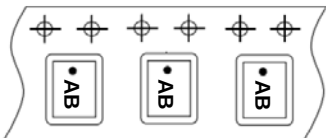
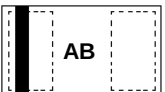
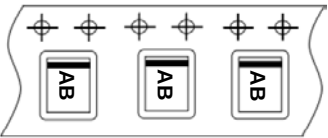
Bottom View

Ordering Information (Note 4)

Device	Packaging	Shipping
SDM20U30LP-7	X1-DFN1006-2	3000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information

SDM20U30LP-7	 Top View Dot Denotes Cathode Side  From date code 1527 (YYWW), this changed to:  Top View Bar Denotes Cathode Side  AB = Product Type Marking Code AB = LM or $\bar{L}M$
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Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	30	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	21	V
Maximum (Peak) Forward Current	I _{FM}	200	mA
Peak Forward Surge Current	I _{FSM}	1.0	A
8.3ms Half Sine			

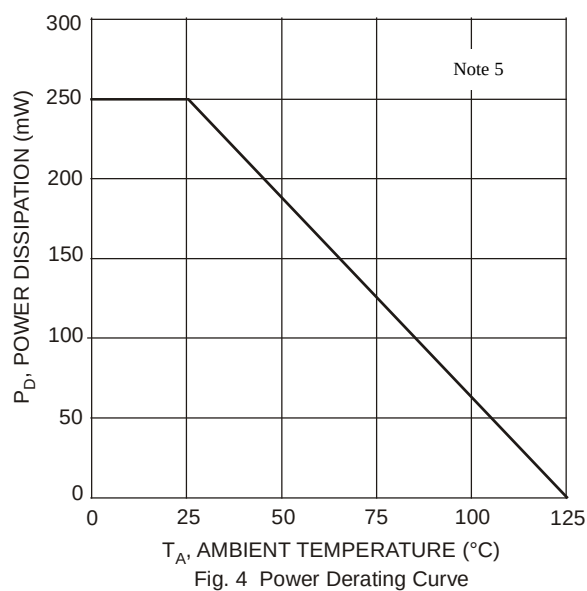
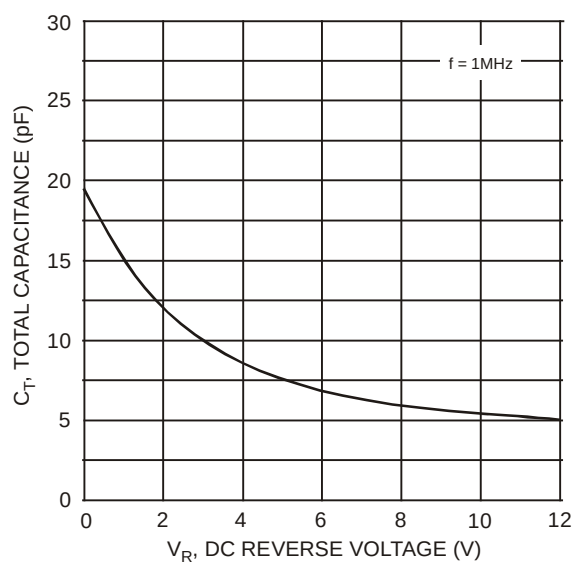
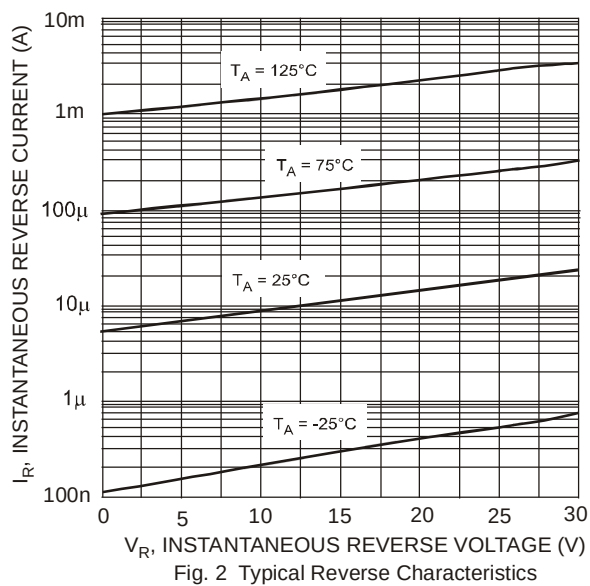
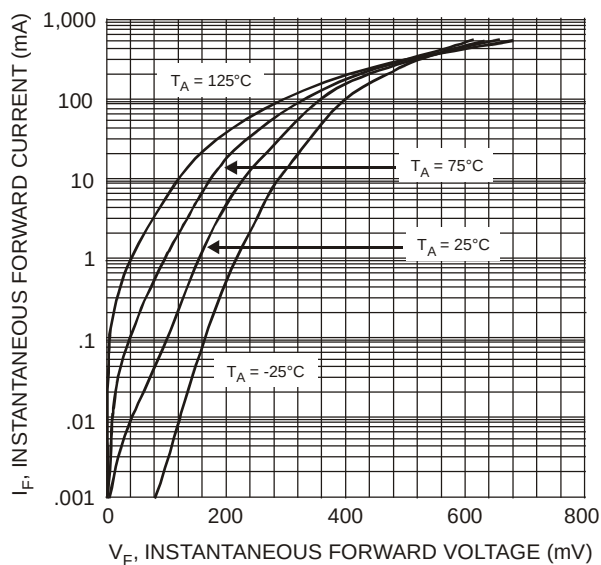
Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation	P _D	250	mW
Thermal Resistance, Junction to Ambient Air (Note 5)	R _{ΘJA}	400	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +125	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Breakdown Voltage (Note 6)	V _{(BR)R}	30	—	—	V	I _R = 150μA
Forward Voltage Drop	V _F	—	—	350 575	mV	I _F = 20mA I _F = 200mA
Peak Reverse Current (Note 6)	I _R	—	—	150 30	μA	V _R = 30V V _R = 10V
Total Capacitance	C _T	—	20	—	pF	V _R = 0V, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	3	—	nS	I _F = I _R = 10mA, I _{R(REC)} = 1mA, R _L = 100Ω

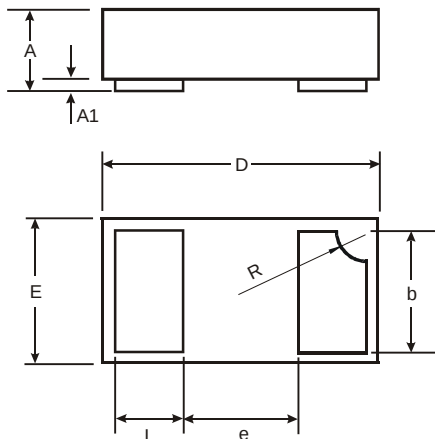
Notes: 5. Device mounted on FR-4 substrate PCB, with minimum recommended pad layout.
6. Short duration pulse test used to minimize self-heating effect.



Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X1-DFN1006-2

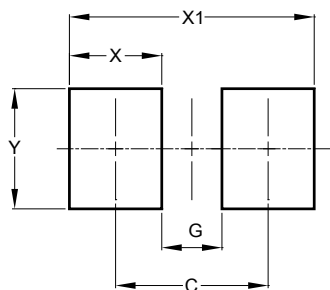


X1-DFN1006-2			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0	0.05	0.03
b	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.40
L	0.20	0.30	0.25
R	0.05	0.15	0.10
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X1-DFN1006-2



Dimension s	Value (in mm)
C	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70

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